

OPAx365-Q1 50MHz、低歪み、高 CMRR、レール・ツー・レール I/O、 単一電源オペアンプ

1 特長

- ・ 車載アプリケーション向けに認定済み
- ・ 下記内容で AEC-Q100 認定済み
 - デバイス温度グレード 1: -40°C ~ 125°C の周囲動作温度範囲
 - デバイス HBM ESD 分類レベル H2
 - デバイス CDM ESD 分類レベル C3B
- ・ OPA2365-Q1 機能安全対応:
 - 機能安全システムの設計に役立つ資料を利用可能
- ・ ゲイン帯域幅: 50MHz
- ・ ゼロ・クロスオーバー歪みトポロジ
 - 優れた THD+N: 0.0004%
 - CMRR: 100 dB (最小)
 - レール・ツー・レール入出力
 - 電源レールを 100mV 超える入力
- ・ 低ノイズ: 100 kHz で 4.5 nV/√Hz
- ・ スルー・レート: 25 V/μs
- ・ 高速セトリング: 0.3μs + 0.01%
- ・ 高精度
 - 低オフセット: 100μV
 - 低入力バイアス電流: 0.2pA
- ・ 2.2V ~ 5.5V で動作

2 アプリケーション

- ・ 車載用
- ・ ADAS (先進運転支援システム)
- ・ HEV/EV とパワートレイン
- ・ ボディ/ライティング
- ・ 死角検出
- ・ エンジン制御ユニット
- ・ DC/DC コンバータ
- ・ 短距離から中距離のレーダー
- ・ 衝突警報
- ・ 産業用
- ・ ヘッド・アップ・ディスプレイ

3 説明

OPAx365-Q1 は、ゼロ・クロスオーバー・ファミリのレール・ツー・レール、高性能、CMOS オペアンプであり、非常に低電圧の単一電源アプリケーション用に最適化されています。レール・ツー・レール入出力、低ノイズ (4.5nV/√Hz)、高速動作 (50MHz のゲイン帯域幅) により、これらのデバイスはサンプリング・データ・コンバータ (ADS7822-Q1 や ADS1115-Q1 など) の駆動、特に短距離から中距離レーダー・アプリケーションに最適です。OPAx365-Q1 ファミリのオペアンプは、DC/DC コンバータの HEV / EV およびパワートレイン・アプリケーションや、エンジン制御ユニットのトランスミッション制御にも適しています。

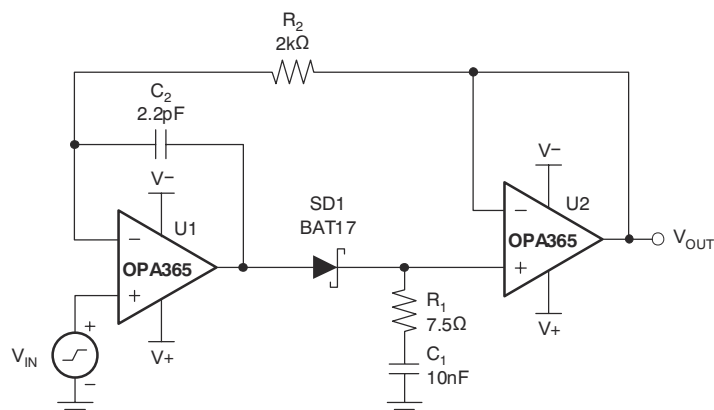
特別な長所として、同相除去率 (CMRR) が非常に優れていること、入力ステージにクロスオーバー歪みがないこと、入力インピーダンスが高いこと、レール・ツー・レール入出力が挙げられます。入力同相範囲には、負と正の電源の両方が含まれています。出力電圧のスイングは、レールから 10mV の範囲内です。

OPA365-Q1 (シングル・バージョン) は 5 ピンの SOT-23 パッケージで供給されます。OPA2365-Q1 (デュアル・バージョン) は 8 ピンの SOIC パッケージで供給されます。すべてのバージョンは、-40°C ~ 125°C での動作が規定されています。シングル・バージョンとデュアル・バージョンは同じ仕様で、設計の柔軟性を最大限に高めます。

製品情報 (1) (1 ページ)

型番	パッケージ	本体サイズ (公称)
OPA2365-Q1	SOIC (8)	4.90mm × 3.91mm
OPA365-Q1	SOT-23 (5)	2.90mm × 1.60mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。



高速セトリング・ピーク検出器



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4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision D (December 2015) to Revision E (November 2020)	Page
• 文書全体にわたって表、図、相互参照の採番方法を更新.....	1
• 「特長」セクションに機能安全対応 - ドキュメント情報を追加.....	1
• Updated <i>Related Documentation</i> section	22

Changes from Revision C (April 2012) to Revision D (December 2015)	Page
• 「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加。.....	1

Changes from Revision B (January 2012) to Revision C (April 2012)	Page
• Added another row with V_{OS} for OPA2365-Q1 only.....	5
• Changed I_Q upper limit to 5.3 from 5.5.....	5

5 Pin Configuration and Functions

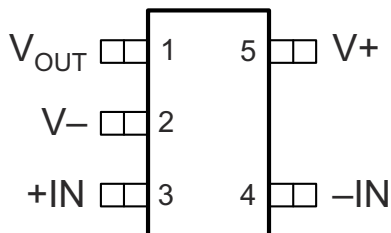


图 5-1. DBV Package 5-Pin SOT-23 Top View

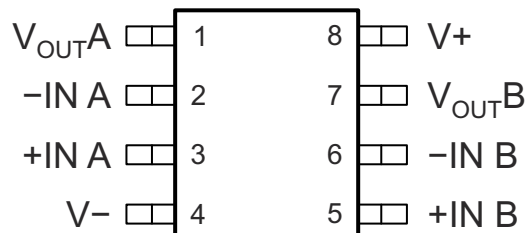


图 5-2. D Package 8-Pin SOIC Top View

表 5-1. Pin Functions

PIN			I/O	DESCRIPTION
NAME	SOT-23	SOIC		
$+IN$	3	—	I	Noninverting input
$-IN$	4	—	I	Inverting input
$+IN A$	—	3	I	Noninverting input
$-IN A$	—	2	I	Inverting input
$+IN B$	—	5	I	Noninverting input
$-IN B$	—	6	I	Inverting input
$V+$	5	8	I	Positive (highest) supply
$V-$	4	4	I	Negative (lowest) supply
V_{OUT}	1	—	O	Output
V_{OUTA}	—	1	O	Output
V_{OUTB}	—	7	O	Output

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage		5.5	V
V _I	Signal input terminals, voltage ⁽²⁾	(V ₋) - 0.5	(V ₊) + 0.5	V
I _I	Signal input terminals, current ⁽²⁾	-10	10	mA
t _{OSC}	Output short-circuit duration ⁽³⁾	Continuous		
T _{OP}	Operating temperature	-40	150	°C
T _J	Junction temperature		150	°C
T _{stg}	Storage temperature	-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current-limited to 10 mA or less.
- (3) Short-circuit to ground, one amplifier per package

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 ⁽¹⁾	±2000
		Charged-device model (CDM), per AEC Q100-011	±750

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V _S	Supply voltage V ₋ to V ₊	2.2	3.3	5.5	V
T _A	Operating free-air temperature	-40	25	125	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		OPA2365-Q1	OPA365-Q1	UNIT
		D (SOIC)	DBV (SOT-23)	
		8 PINS	5 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	115.5	208.8	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	60.1	123.7	°C/W
R _{θJB}	Junction-to-board thermal resistance	56.9	54.6	°C/W
ψ _{JT}	Junction-to-top characterization parameter	9.5	37.2	°C/W
ψ _{JB}	Junction-to-board characterization parameter	56.3	36.3	°C/W

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

$V_S = 2.2\text{ V to }5.5\text{ V}$, $R_L = 10\text{ k}\Omega$ connected to $V_S/2$, $V_{CM} = V_S/2$, and $V_{OUT} = V_S/2$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T _A ⁽¹⁾	MIN	TYP	MAX	UNIT
OFFSET VOLTAGE							
V _{OS}	Input offset voltage		25°C		100	200	μV
V _{OS} ⁽³⁾	Input offset voltage		25°C		100	230	μV
dV _{OS} / dT	Input offset voltage drift		Full range		1		μV/°C
PSRR	Input offset voltage vs power supply	V _S = 2.2 V to 5.5 V	Full range		10	100	μV/V
	Channel separation, DC		25°C		0.2		μV/V
INPUT BIAS CURRENT							
I _B	Input bias current		25°C		±0.2	±10	pA
			Full range	See セクション 6.6			
I _{OS}	Input offset current		25°C		±0.2	±10	pA
NOISE							
e _n	Input voltage noise	f = 0.1 Hz to 10 Hz	25°C		5		μV _{PP}
e _n	Input voltage noise density	f = 100 kHz	25°C		4.5		nV/√ Hz
i _n	Input current noise density	f = 10 kHz	25°C		4		fA/√ Hz
INPUT VOLTAGE RANGE							
V _{CM}	Common-mode voltage		25°C	(V-) – 0.1	(V+) + 0.1		V
CMRR	Common-mode rejection ratio	(V-) – 0.1 V ≤ V _{CM} ≤ (V+) + 0.1 V	Full range	100	120		dB
INPUT CAPACITANCE							
	Differential		25°C		6		pF
	Common-mode		25°C		2		pF
OPEN-LOOP GAIN							
A _{OL}	Open-loop voltage gain	R _L = 10 kΩ, 100 mV < V _O < (V+) – 100 mV	Full range	100	120		dB
		R _L = 600 Ω, 200 mV < V _O < (V+) – 200 mV	25°C	100	120		
		R _L = 600 Ω, 200 mV < V _O < (V+) – 200 mV	Full range	94			
FREQUENCY RESPONSE							
GBW	Gain-bandwidth product		25°C		50		MHz
SR	Slew rate	V _S = 5 V, G = 1	25°C		25		V/μs
t _S	Settling time	0.1%, V _S = 5 V, 4-V Step, G = 1	25°C		200		ns
		0.01%, V _S = 5 V, 4-V Step, G = 1	25°C		300		
	Overload recovery time	V _S = 5 V, V _{IN} × Gain > V _S	25°C		< 0.1		μs
THD+N	Total harmonic distortion + noise ⁽²⁾	V _S = 5 V, R _L = 600 Ω, V _O = 4 V _{PP} , G = 1, f = 1 kHz	25°C		0.0004%		
OUTPUT							
	Voltage output swing from rail	R _L = 10 kΩ, V _S = 5.5 V	Full range		10	20	mV
I _{SC}	Short-circuit current		25°C		±65		mA
C _L	Capacitive load drive		25°C	See セクション 6.6			
	Open-loop output impedance	f = 1 MHz, I _O = 0	25°C		30		Ω
POWER SUPPLY							
V _S	Specified voltage		25°C	2.2		5.5	V
I _Q	Quiescent current per amplifier	I _O = 0	25°C		4.6	5	mA
			Full range			5.3	

$V_S = 2.2\text{ V to }5.5\text{ V}$, $R_L = 10\text{ k}\Omega$ connected to $V_S/2$, $V_{CM} = V_S/2$, and $V_{OUT} = V_S/2$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T_A ⁽¹⁾	MIN	TYP	MAX	UNIT
TEMPERATURE RANGE						
Specified		25°C	–40		125	°C
θ_{JA} Thermal resistance	SOT23-5	25°C				°C/W
	SO-8	25°C		200		

- (1) Full range $T_A = -40^\circ\text{C to }125^\circ\text{C}$
 (2) Third-order filter, bandwidth 80 kHz at –3 dB.
 (3) For OPA2365-Q1 only

6.6 Typical Characteristics

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $C_L = 0\text{ pF}$ (unless otherwise noted)

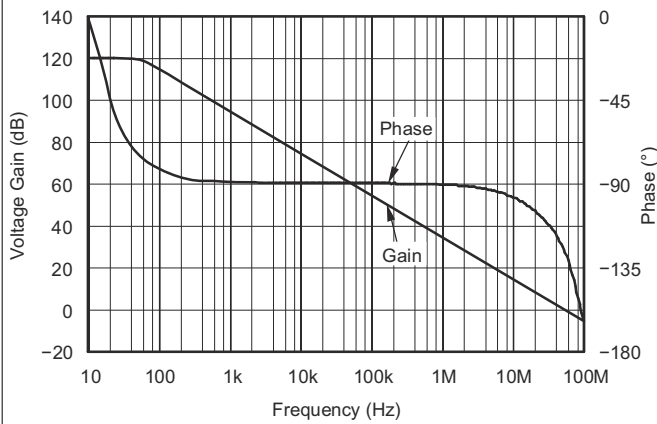


FIG 6-1. Open-Loop Gain and Phase vs Frequency

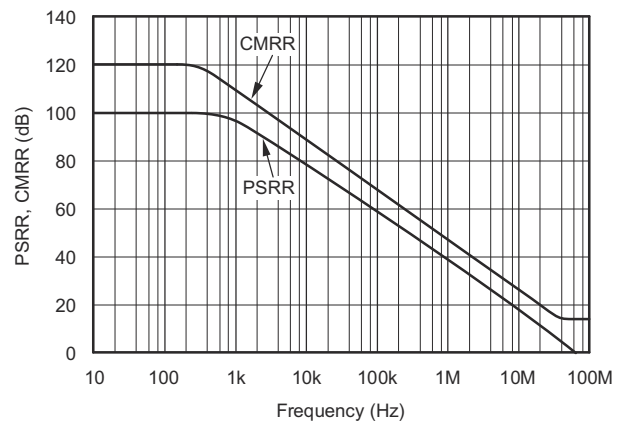


FIG 6-2. Power Supply and Common Mode Rejection Ratio vs Frequency

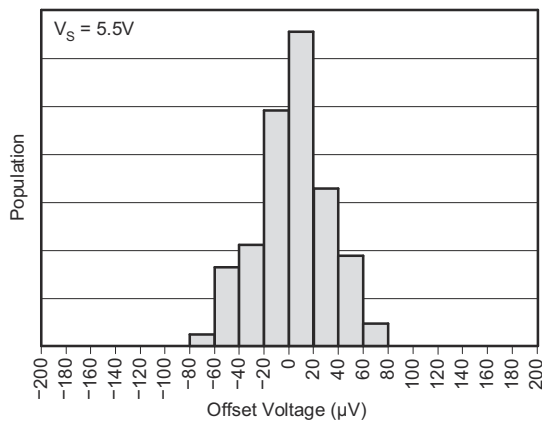


FIG 6-3. Offset Voltage Production Distribution

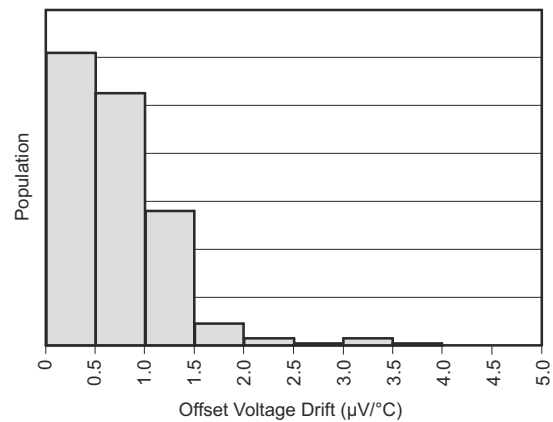


FIG 6-4. Offset Voltage Drift Production Distribution

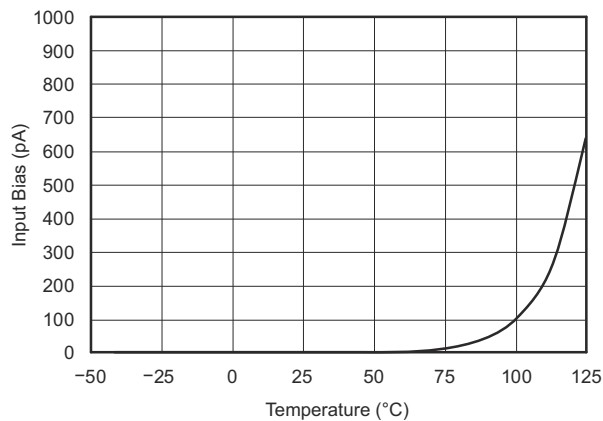


FIG 6-5. Input Bias Current vs Temperature

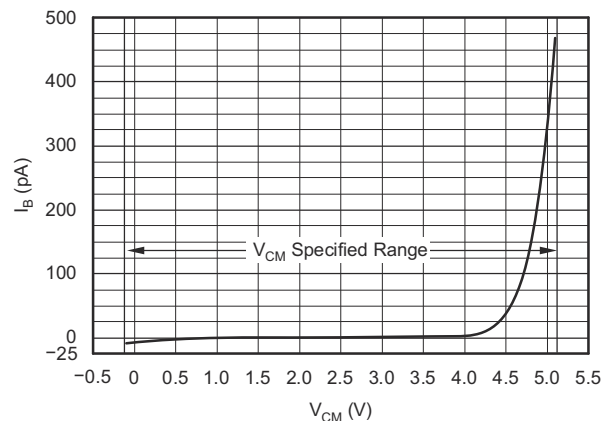


FIG 6-6. Input Bias Current vs Common Mode Voltage

6.6 Typical Characteristics (continued)

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $C_L = 0\text{ pF}$ (unless otherwise noted)

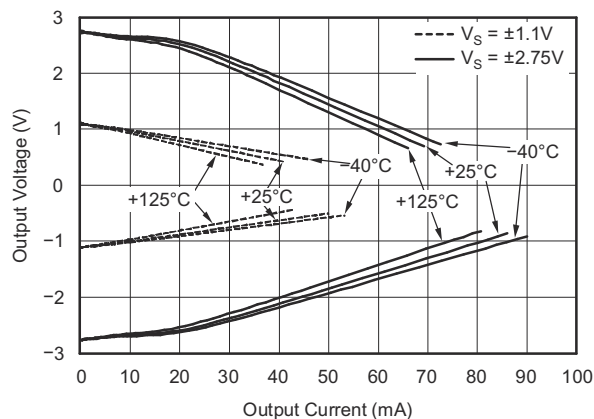


FIG 6-7. OPA365-Q1 Output Voltage vs Output Current

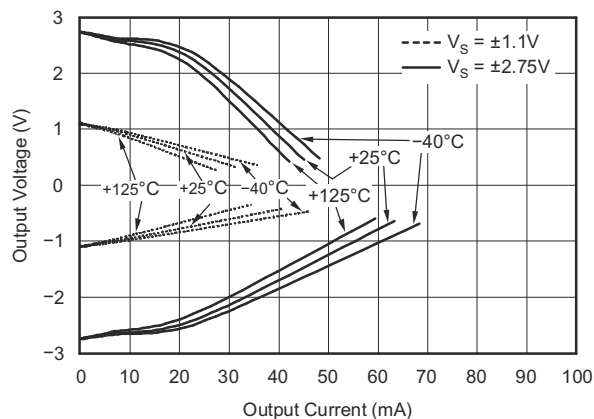


FIG 6-8. OPA2365-Q1 Output Voltage Swing vs Output Current

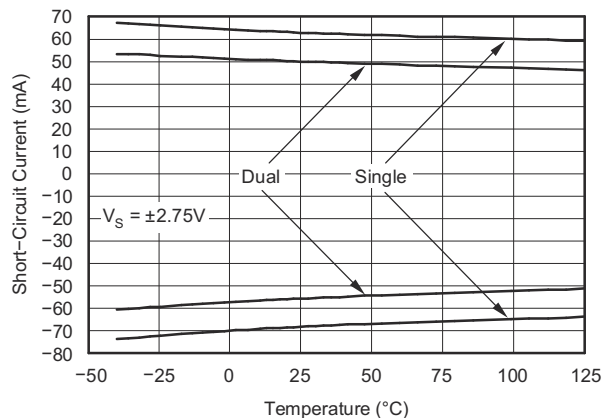


FIG 6-9. Short-Circuit Current vs Temperature

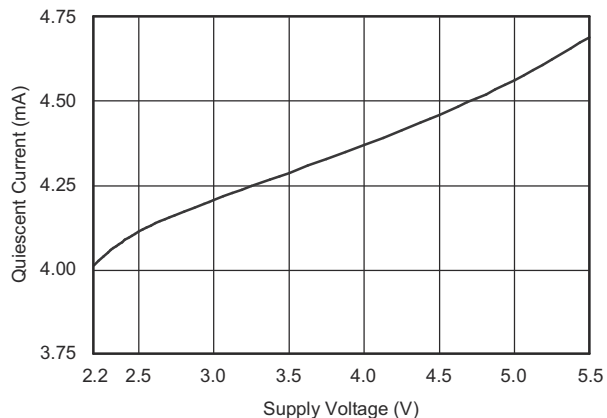


FIG 6-10. Quiescent Current vs Supply Voltage

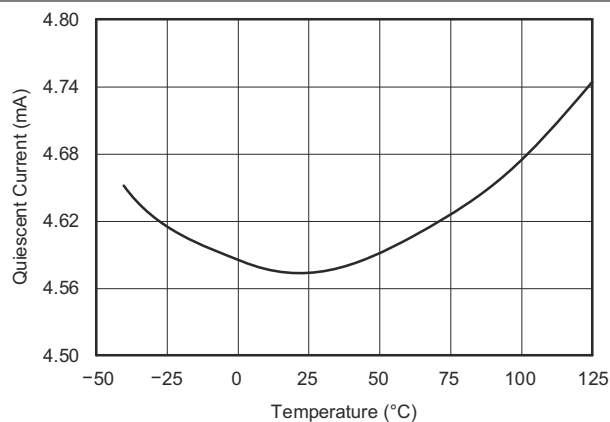


FIG 6-11. Quiescent Current vs Temperature

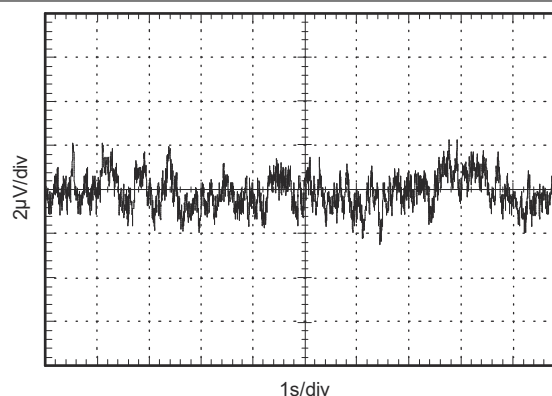
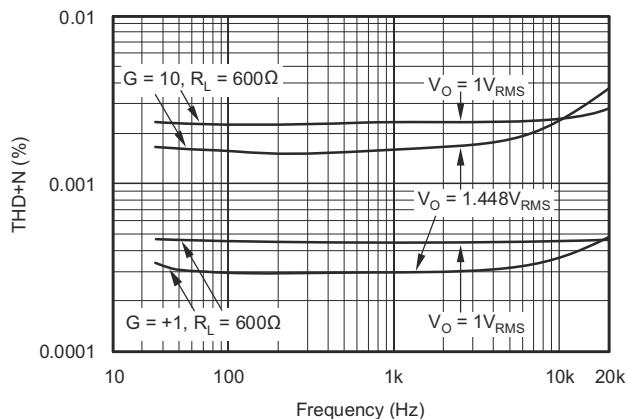


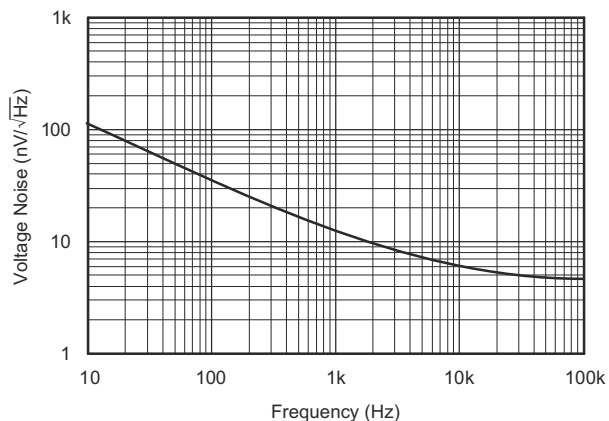
FIG 6-12. 0.1-Hz to 10-Hz Input Voltage Noise

6.6 Typical Characteristics (continued)

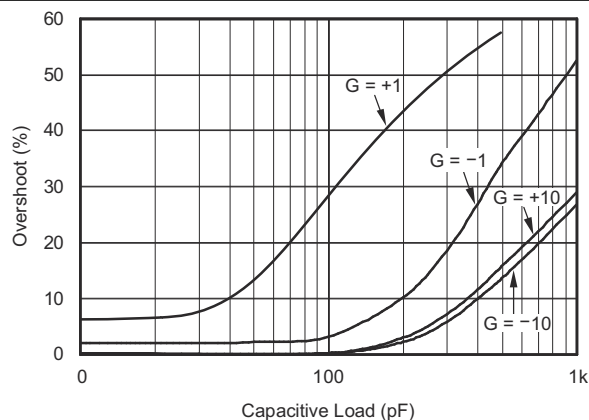
$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $C_L = 0\text{ pF}$ (unless otherwise noted)



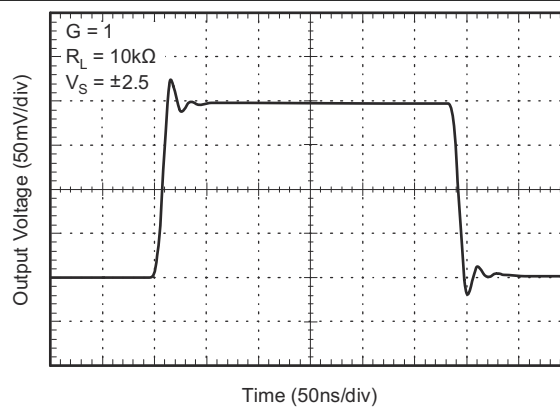
6-13. Total Harmonic Distortion + Noise vs Frequency



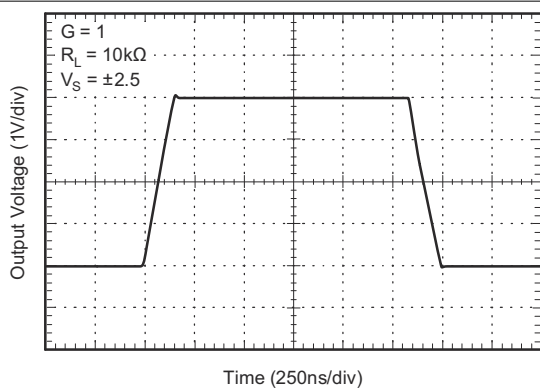
6-14. Input Voltage Noise Spectral Density



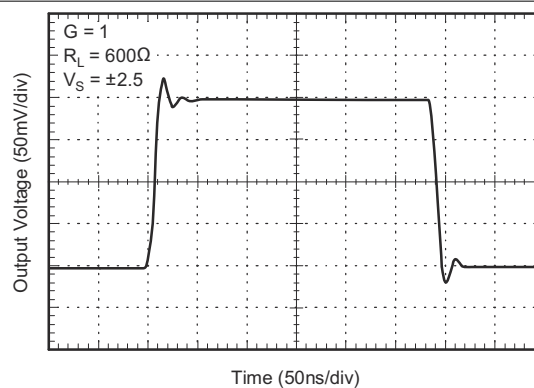
6-15. Overshoot vs Capacitive Load



6-16. Small-Signal Step Response



6-17. Large-Signal Step Response



6-18. Small-Signal Step Response

6.6 Typical Characteristics (continued)

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $C_L = 0\text{ pF}$ (unless otherwise noted)

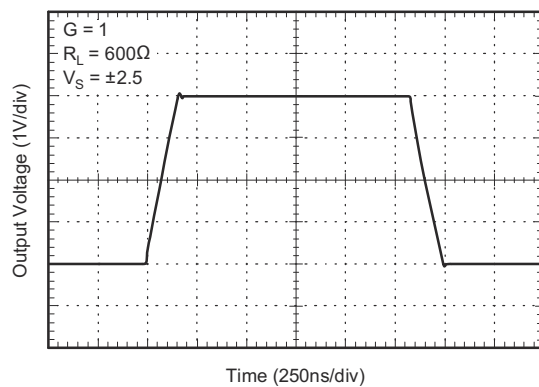


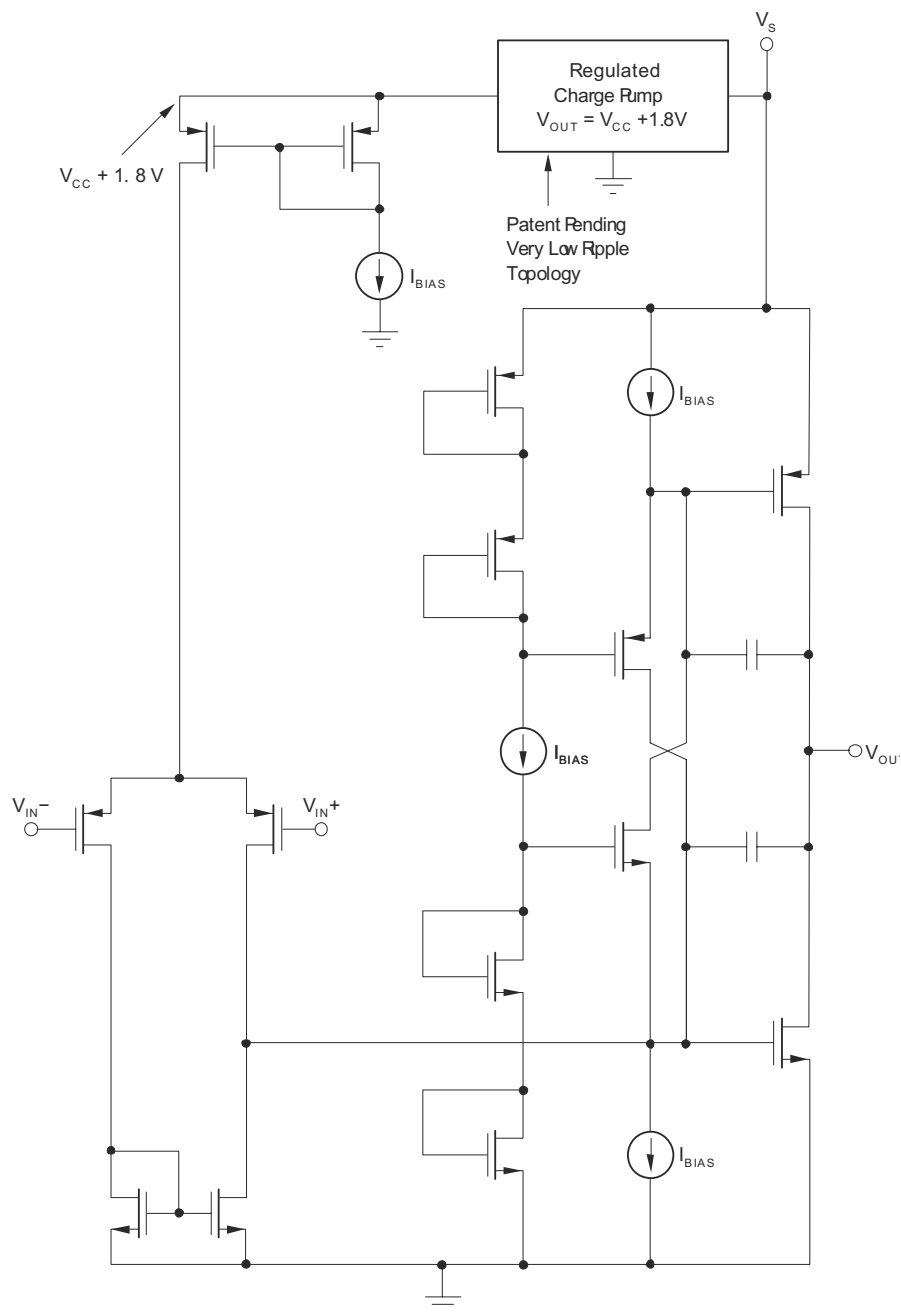
FIG 6-19. Large-Signal Step Response

7 Detailed Description

7.1 Overview

The OPAX365-Q1 zero-crossover family of rail-to-rail, high-performance, CMOS operational amplifiers are optimized for very low voltage, single-supply applications. Their rail-to-rail input and output, low-noise ($4.5 \text{ nV}/\sqrt{\text{Hz}}$), and high-speed operation (50-MHz gain bandwidth) make these devices ideal for driving sampling analog-to-digital converters (ADCs). Applications include audio, signal conditioning, and sensor amplification. The high-gain bandwidth of 50 MHz makes this family suited for amplifying low signal levels and high frequency such as radar signal processing .

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Operating Characteristics

The OPA365-Q1 amplifier parameters are fully specified from 2.2 V to 5.5 V. Many of the specifications apply from -40°C to 125°C . Parameters that can exhibit significant variance with regard to operating voltage or temperature are presented in [セクション 6.6](#).

7.3.2 Basic Amplifier Configurations

As with other single-supply operational amplifiers, the OPA365-Q1 may be operated with either a single supply or dual supplies (see [図 7-1](#)). A typical dual-supply connection is shown in [図 7-1](#), which is accompanied by a single-supply connection. The OPA365-Q1 device is configured as a basic inverting amplifier with a gain of -10 V/V. The dual-supply connection has an output voltage centered on zero, while the single-supply connection has an output centered on the common-mode voltage V_{CM} . For the circuit shown, this voltage is 1.5 V, but may be any value within the common-mode input voltage range. The OPA365-Q1 V_{CM} range extends 100 mV beyond the power-supply rails.

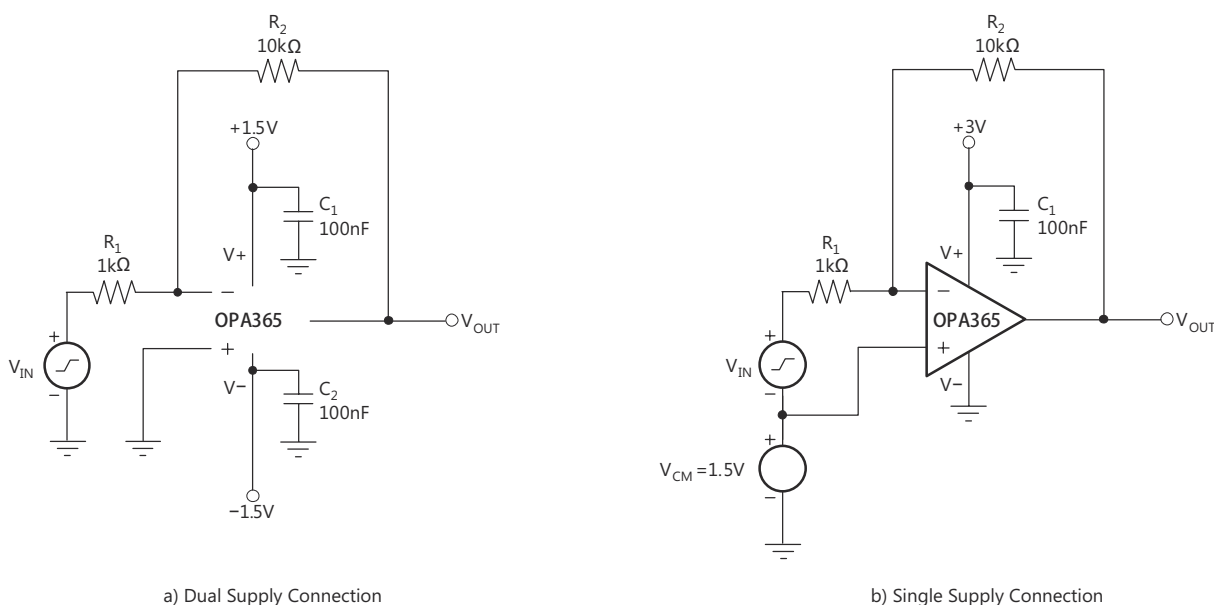


図 7-1. Basic Circuit Connections

[図 7-2](#) shows a single-supply, electret microphone application where V_{CM} is provided by a resistive divider. The divider also provides the bias voltage for the electret element.

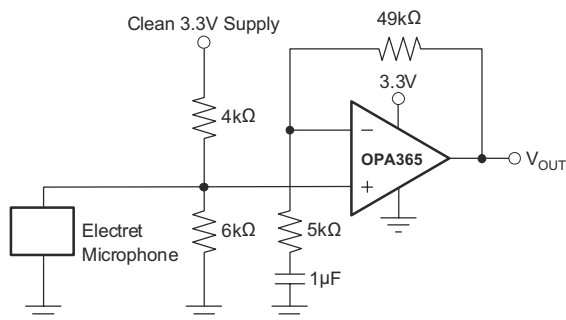


図 7-2. Microphone Preamplifier

7.3.3 Input and ESD Protection

The OPA365-Q1 device incorporates internal electrostatic discharge (ESD) protection circuits on all pins. In the case of input and output pins, this protection primarily consists of current steering diodes connected between the input and power-supply pins. These ESD protection diodes also provide in-circuit, input overdrive protection, provided that the current is limited to 10 mA as stated in the [セクション 6.1](#). [図 7-3](#) shows how a series input resistor may be added to the driven input to limit the input current. The added resistor contributes thermal noise at the amplifier input and its value should be kept to the minimum in noise-sensitive applications.

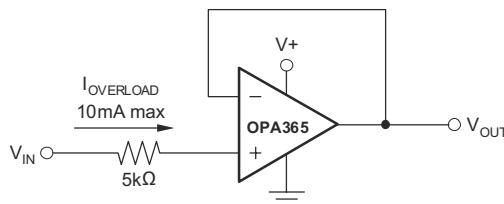


図 7-3. Input Current Protection

7.3.4 Rail-to-Rail Input

The OPA365-Q1 product family features true rail-to-rail input operation, with supply voltages as low as ± 1.1 V (2.2 V). A unique zero-crossover input topology eliminates the input offset transition region typical of many rail-to-rail, complementary stage operational amplifiers. This topology also allows the OPA365-Q1 device to provide superior common-mode performance over the entire input range, which extends 100 mV beyond both power-supply rails, as shown in [図 7-4](#). When driving ADCs, the highly linear VCM range of the OPA365-Q1 device assures that the operational amplifier/ADC system linearity performance is not compromised.

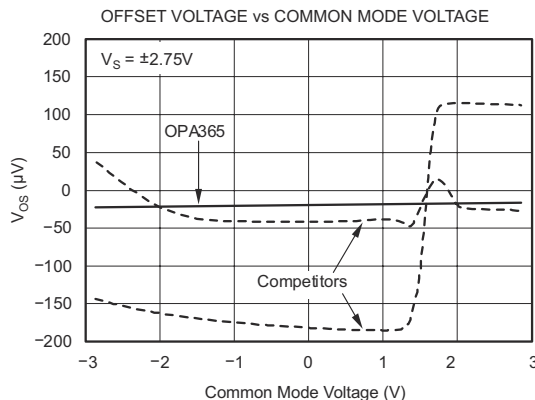


図 7-4. OPA365-Q1 Has Linear Offset Over the Entire Common-Mode Range

7.4 Device Functional Modes

The OPAX365-Q1 family of devices is powered on when the supply is connected. The device can be operated as a single-supply operational amplifier or a dual-supply amplifier depending on the application.

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

8.1.1 Capacitive Loads

The OPA365-Q1 device may be used in applications where driving a capacitive load is required. As with all operational amplifiers, there may be specific instances where the OPA365-Q1 device can become unstable, leading to oscillation. The particular operational amplifier circuit configuration, layout, gain and output loading are some of the factors to consider when establishing whether an amplifier will be stable in operation. An operational amplifier in the unity-gain (1 V/V) buffer configuration and driving a capacitive load exhibits a greater tendency to be unstable than an amplifier operated at a higher noise gain. The capacitive load, in conjunction with the operational amplifier output resistance, creates a pole within the feedback loop that degrades the phase margin. The degradation of the phase margin increases as the capacitive loading increases.

When operating in the unity-gain configuration, the OPA365-Q1 device remains stable with a pure capacitive load up to approximately 1 nF. The equivalent series resistance (ESR) of some very large capacitors ($C_L > 1 \mu\text{F}$) is sufficient to alter the phase characteristics in the feedback loop such that the amplifier remains stable. Increasing the amplifier closed-loop gain allows the amplifier to drive increasingly larger capacitance. This increased capability is evident when observing the overshoot response of the amplifier at higher voltage gains. See [Figure 6-15](#).

One technique for increasing the capacitive load drive capability of the amplifier operating in unity gain is to insert a small resistor, typically 10 Ω to 20 Ω , in series with the output; see [Figure 8-1](#). This resistor significantly reduces the overshoot and ringing associated with large capacitive loads. A possible problem with this technique is that a voltage divider is created with the added series resistor and any resistor connected in parallel with the capacitive load. The voltage divider introduces a gain error at the output that reduces the output swing. The error contributed by the voltage divider may be insignificant. For instance, with a load resistance, $R_L = 10 \text{ k}\Omega$, and $R_S = 20 \Omega$, the gain error is only about 0.2%. However, when R_L is decreased to 600 Ω , which the OPA365-Q1 device is able to drive, the error increases to 7.5%.

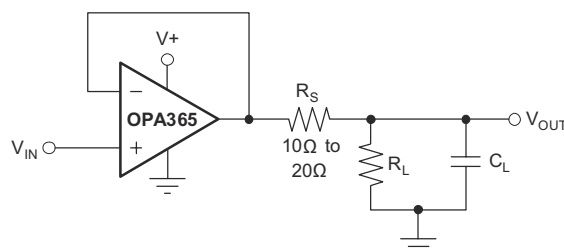


Figure 8-1. Improving Capacitive Load Drive

8.1.2 Achieving an Output Level of Zero Volts (0 V)

Certain single-supply applications require the operational amplifier output to swing from 0 V to a positive full-scale voltage and have high accuracy. An example is an operational amplifier employed to drive a single-supply ADC having an input range from 0 V to 5 V. Rail-to-rail output amplifiers with very light output loading may achieve an output level within millivolts of 0 V (or $+V_S$ at the high end), but not 0 V. Furthermore, the deviation from 0 V only becomes greater as the load current required increases. This increased deviation is a result of limitations of the CMOS output stage.

When a pulldown resistor is connected from the amplifier output to a negative voltage source, the OPA365-Q1 can achieve an output level of 0 V, and even a few millivolts below 0 V. Below this limit, nonlinearity and limiting conditions become evident. [Figure 8-2](#) illustrates a circuit using this technique.

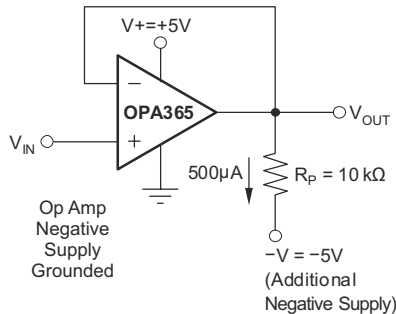


Figure 8-2. Swing-to-Ground

A pulldown current of approximately 500 μA is required when OPA365-Q1 is connected as a unity-gain buffer. A practical termination voltage (V_{NEG}) is -5 V , but other convenient negative voltages also may be used. The pulldown resistor R_L is calculated from $R_L = [(V_O - V_{\text{NEG}})/(500\text{ }\mu\text{A})]$. Using a minimum output voltage (V_O) of 0 V, $R_L = [0\text{ V} - (-5\text{ V})]/(500\text{ }\mu\text{A}) = 10\text{ k}\Omega$. Keep in mind that lower termination voltages result in smaller pulldown resistors that load the output during positive output voltage excursions.

This technique does not work with all operational amplifiers, and should only be applied to operational amplifiers, such as the OPA365-Q1, that have been specifically designed to operate in this manner. Also, operating the OPA365-Q1 output at 0 V changes the output stage operating conditions, resulting in somewhat lower open-loop gain and bandwidth. Keep these precautions in mind when driving a capacitive load because these conditions can affect circuit transient response and stability.

8.1.3 Active Filtering

The OPA365-Q1 device is well-suited for active filter applications requiring a wide bandwidth, fast slew rate, low-noise, and single-supply operational amplifier. [Figure 8-3](#) shows a 500 kHz, 2nd-order, low-pass filter utilizing the multiple-feedback (MFB) topology. The components have been selected to provide a maximally-flat Butterworth response. Beyond the cutoff frequency, roll-off is -40 dB/dec . The Butterworth response is ideal for applications requiring predictable gain characteristics such as the anti-aliasing filter used ahead of an ADC.

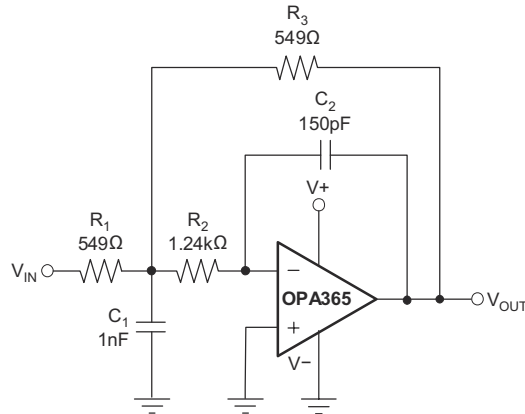


FIG 8-3. Second-Order Butterworth 500-kHz Low-Pass Filter

One point to observe when considering the MFB filter is that the output is inverted, relative to the input. If this inversion is not required, or not desired, a noninverting output can be achieved through one of these options:

1. adding an inverting amplifier;
2. adding an additional 2nd-order MFB stage;
3. using a noninverting filter topology such as the Sallen-Key (shown in FIG 8-4).

MFB and Sallen-Key, low-pass and high-pass filter synthesis is quickly accomplished using TI's FilterPro program. This software is available as a free download at www.ti.com.

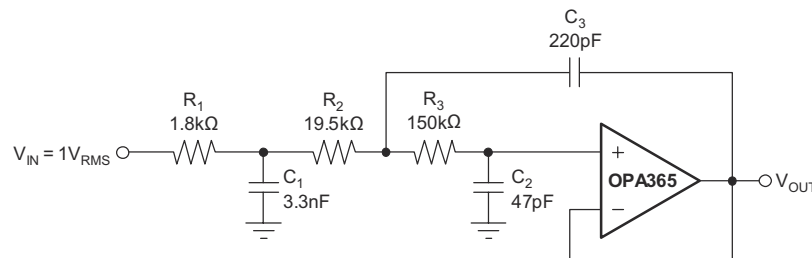


FIG 8-4. Configured as a 3-Pole, 20 kHz, Sallen-Key Filter

8.1.4 Driving an ADS7822-Q1 Analog-to-Digital Converter

The OPAX365-Q1 operational amplifiers are optimized for driving medium to high speed sampling A/D converters. The OPAX365-Q1 op amps buffer the A/D's input capacitance and resulting charge injection while providing signal gain. FIG 8-5 shows the OPAX365-Q1 in a basic noninverting configuration driving the ADS7822-Q1. The ADS7822-Q1 is a 12-bit, micro-power sampling converter in the MSOP-8 package. When used with the low-power, miniature packages of the OPAX365-Q1, the combination is ideal for space-limited, low power applications. In this configuration, an RC network at the A/D's input can be used to filter charge injection.

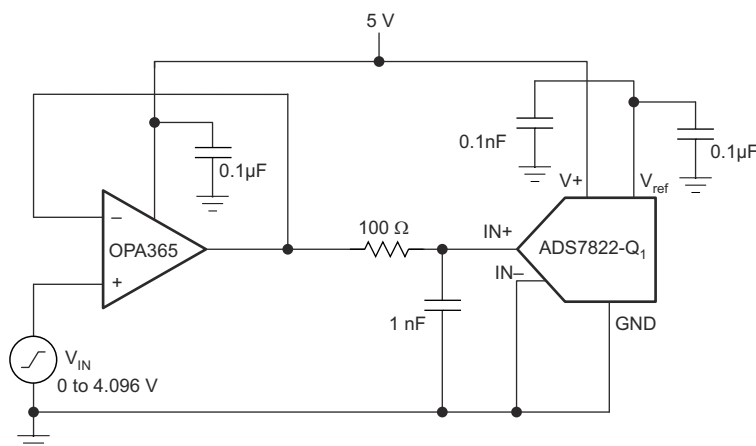


FIG 8-5. Driving the ADS7822-Q1

8.1.5 Driving ADS1115-Q1 Analog-to-Digital Converter

Some applications such as multi-channels mid range radar need selection between channels. OPA2365-Q1 combined with ADS1115-Q1 fit very well for 2 channels radar selection. The circuit in FIG 8-6 shows the same band pass filter but the components can be modified for different desired band pass.

The ADS1115-Q1 inputs are set as differential. the inputs accept up to the ± 2 V. The OPA2365-Q1 flat gain is 100 so the input signal peak is 20 mV.

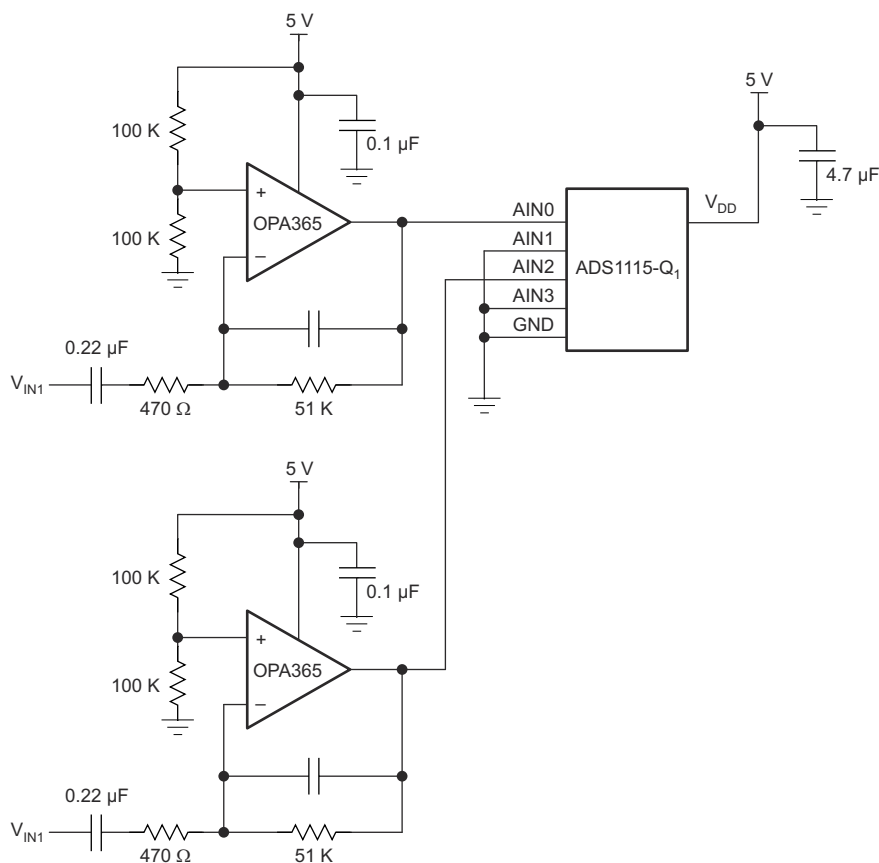


FIG 8-6. Driving the ADS1115-Q1

8.2 Typical Application

8.2.1 Fast Settling Peak Detector

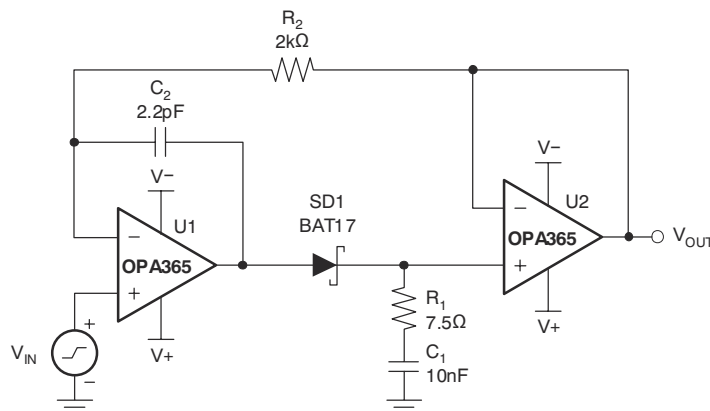


FIG 8-7. Fast Settling Peak Detector Schematic

Some applications require peak signal measurement. High unity gain bandwidth, wide supply voltage range, rail-to-rail input and output, and very low input bias current make the OPA2365-Q1 device very suitable for a peak detector circuit.

8.2.1.1 Design Requirements

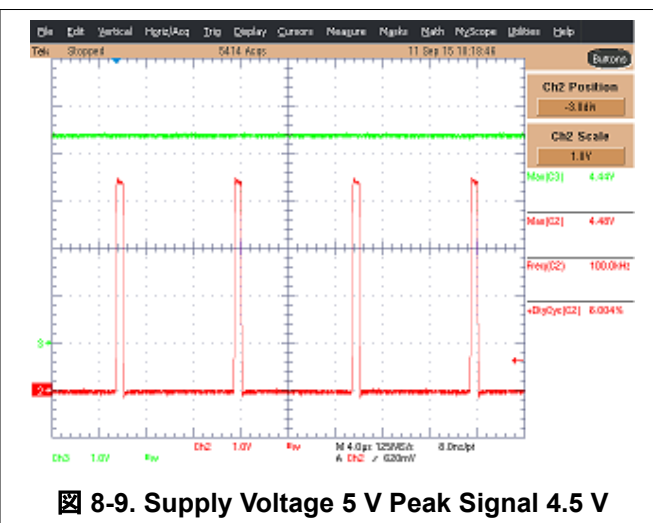
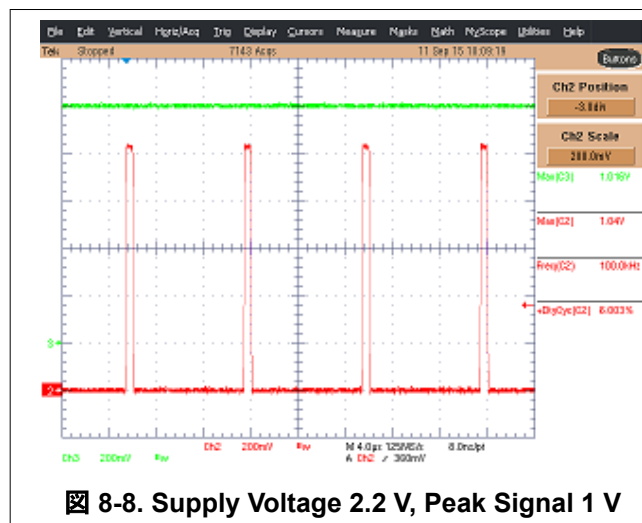
Use the following design parameters for this application:

- Supply voltage: 2.2 V to 5 V
- Input signal: 0 V to 4.5 V
- Input signal frequency: 0 MHz to 1 MHz

8.2.1.2 Detailed Design Procedure

The circuit in FIG 8-7 detects the peak of an input signal and generates a DC output equal to the peak level $V_{OUT} = V_{INpeak}$. The capacitor C1 is charged through the SD1 diode and limiting resistor R1. The only discharging path for C1 is the OPA2365-Q1 very high input impedance. This allows the peak detection of low frequency and low-duty cycle signal.

8.2.1.3 Application Curves



8.2.2 Bandpass Filter 1.5 kHz to 160 kHz and 40-dB Flat Gain

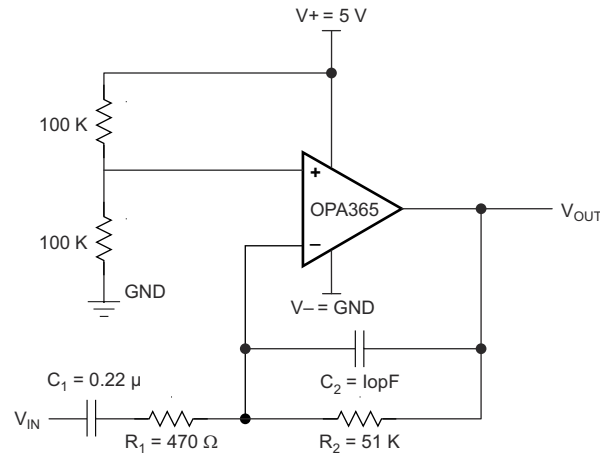


FIG 8-10. Bandpass Filter 1.5 kHz to 160 kHz and 40-dB Flat Gain Schematic

8.2.2.1 Design Requirements

Use the following design parameters for this application:

- Supply voltage: 2.2 V to 5 V
- Input signal: 0 V to 25 mV
- Input signal frequency: 0 MHz to 1 MHz

8.2.2.2 Detailed Design Procedure

Some applications need bandpass filter—that is, radar or audio signal preprocessing. The cross over frequencies and flat gain can be adjusted by changing the resistors and capacitors value according to applications.

The circuit is designed for 5-V supply and 20-mV input signal. With a flat gain of 100 dB or 40 dB, the peak output signal is 2 V. The reference signal is at half way of 5 V, which is 2.5 V.

$$\text{The transfer function or gain} = \frac{V_{\text{out}}}{V_{\text{in}}} = - \frac{R_2 C_1 S}{(1 + R_1 C_1 S)(1 + R_2 C_2 S)} \quad (1)$$

$$\text{A zero at} = \frac{1}{2\pi R_2 C_1} = 14.2 \text{ Hz} \quad (2)$$

$$\text{A pole at} = \frac{1}{2\pi R_1 C_1} = 1.54 \text{ KHz} \quad (3)$$

$$\text{A pole at} = \frac{1}{2\pi R_2 C_2} = 156 \text{ KHz} \quad (4)$$

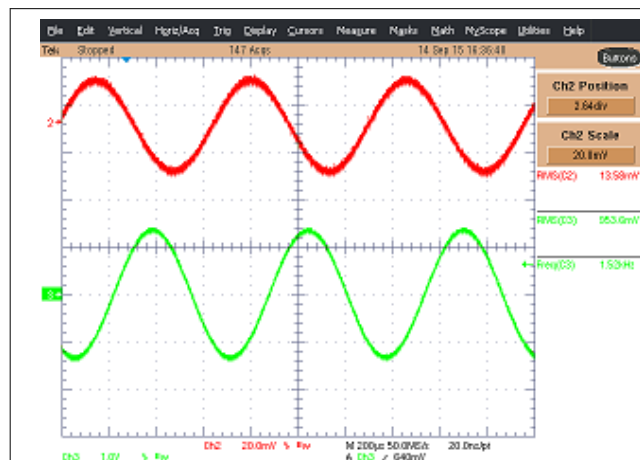
$$\text{Flat Gain of 100 or 40 dB between 1.54 kHz and 156 kHz} \quad (5)$$

$$20 \text{ dB/decade below 1.54 KHz} \quad (6)$$

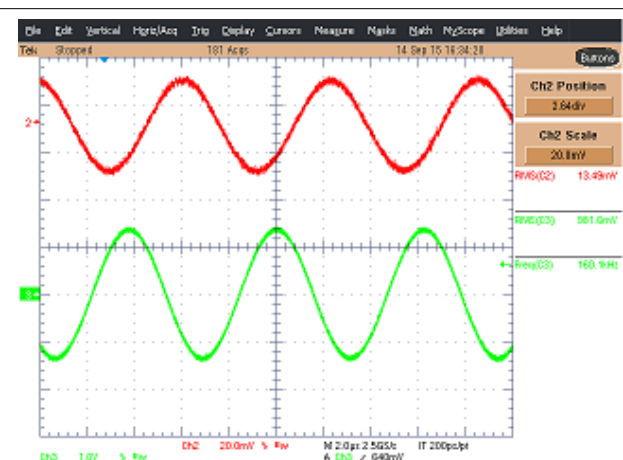
$$-20 \text{ dB/decade above 156 kHz} \quad (7)$$

$$\text{Bandpass between 1.54 kHz and 156 kHz} \quad (8)$$

8.2.2.3 Application Curves



8-11. Gain Is -3 dB Below the Flat Gain at 1.5 kHz



8-12. Gain Is -3 dB Above the Flat Gain at 160 kHz

9 Power Supply Recommendations

The OPAx365-Q1 family of devices is specified for operation from 2.2 V to 5.5 V (± 1.1 V to ± 2.75 V); many specifications apply from -40°C to 125°C . The [セクション 6.6](#) presents parameters that can exhibit significant variance with regard to operating voltage or temperature.

CAUTION

Supply voltages larger than 7 V can permanently damage the device (see [セクション 6.1](#)).

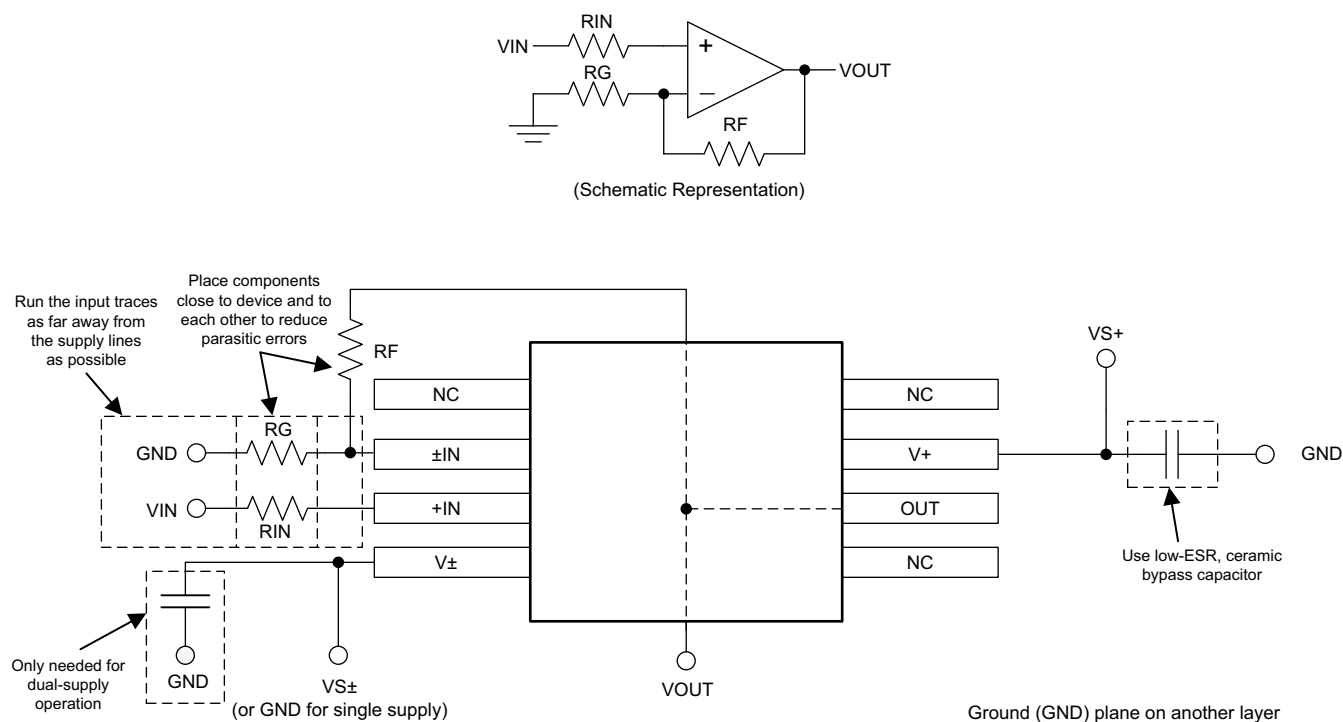
Place 0.1- μF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high impedance power supplies. For more detailed information on bypass capacitor placement, see [セクション 10.1](#).

10 Layout

10.1 Layout Guidelines

The OPA365-Q1 is a wideband amplifier. To realize the full operational performance of the device, good high-frequency printed-circuit-board (PCB) layout practices are required. Low-loss 0.1- μ F bypass capacitors must be connected between each supply pin and ground as close to the device as possible. The bypass capacitor traces should be designed for minimum inductance.

10.2 Layout Example



10-1. Layout Recommendation

11 Device and Documentation Support

11.1 Documentation Support

11.1.1 Related Documentation

Texas Instruments, [ADS1258 16-Channel, 24-Bit Analog-to-Digital Converter data sheet](#)

11.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

11.3 Trademarks

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11.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
OPA2365AQDRQ1	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	O2365Q
OPA2365AQDRQ1.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	O2365Q
OPA365AQDBVRQ1	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	OTNQ
OPA365AQDBVRQ1.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	OTNQ

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

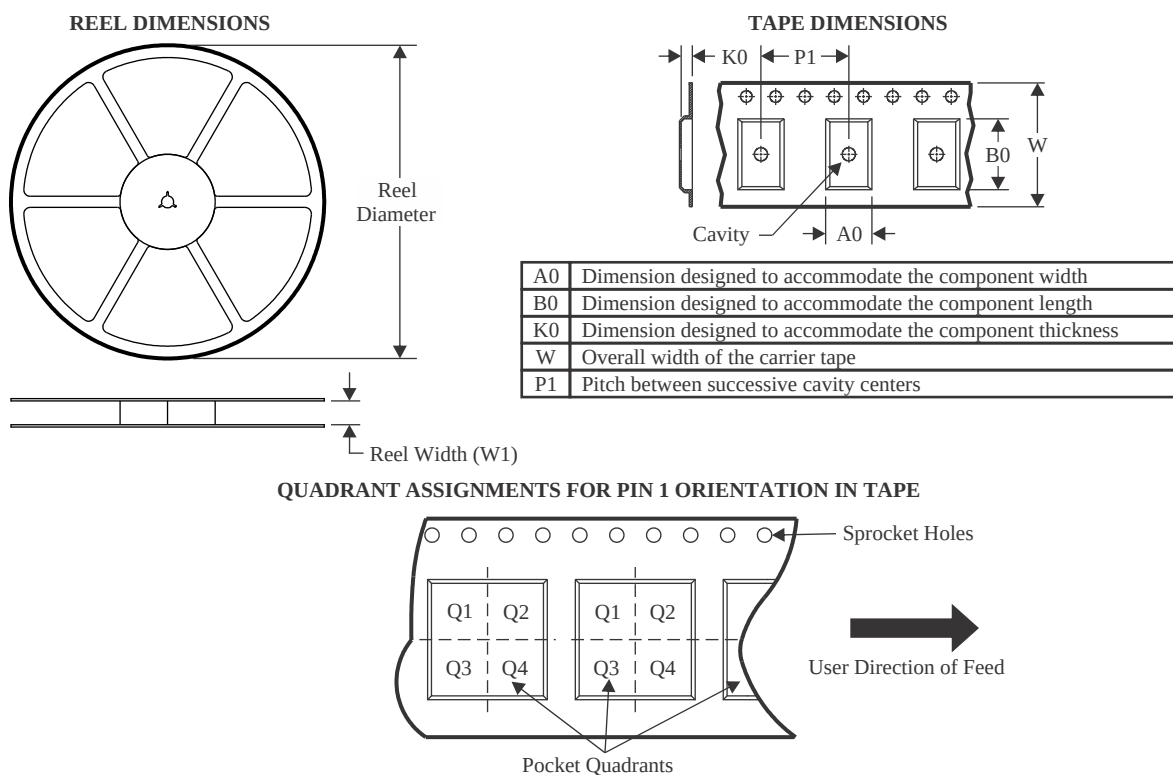
OTHER QUALIFIED VERSIONS OF OPA2365-Q1, OPA365-Q1 :

- Catalog : [OPA2365](#), [OPA365](#)
- Enhanced Product : [OPA365-EP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

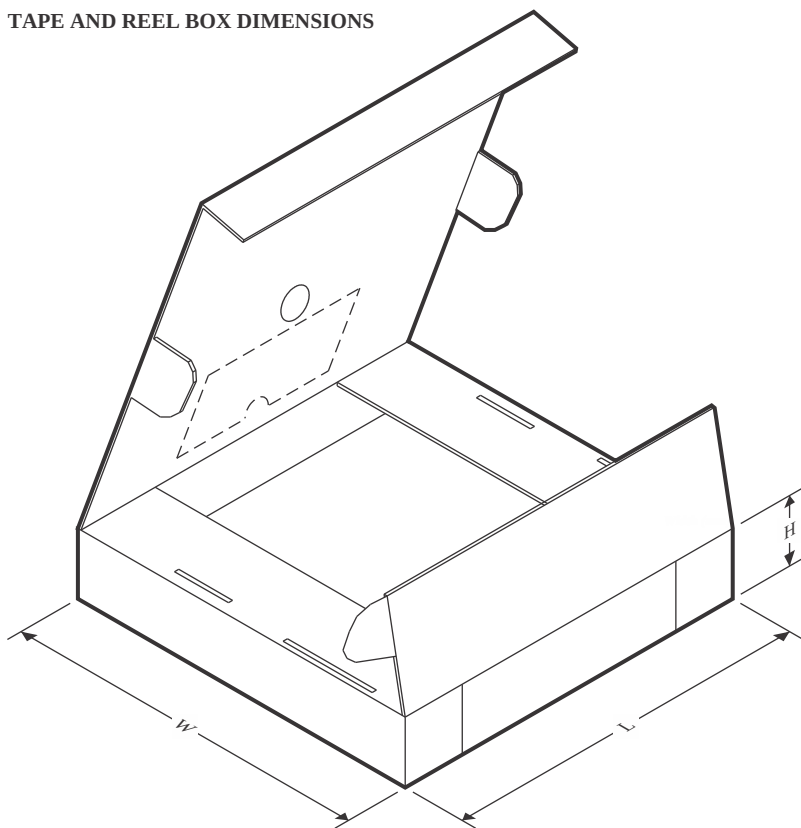
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2365AQDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA365AQDBVRQ1	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

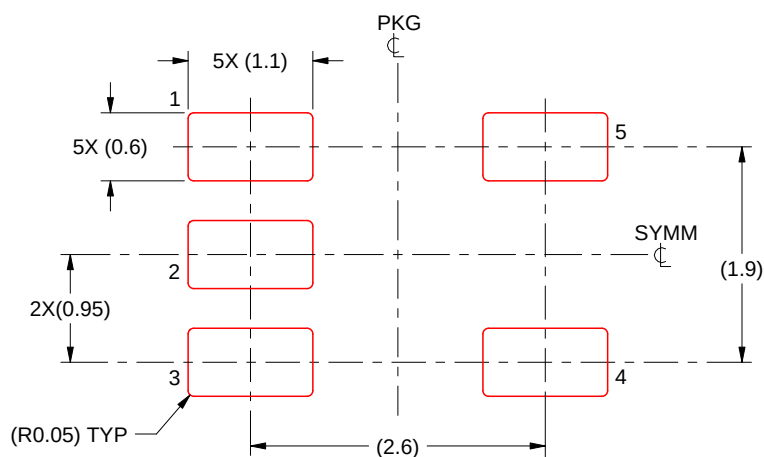
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2365AQDRQ1	SOIC	D	8	2500	356.0	356.0	35.0
OPA365AQDBVRQ1	SOT-23	DBV	5	3000	200.0	183.0	25.0

EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

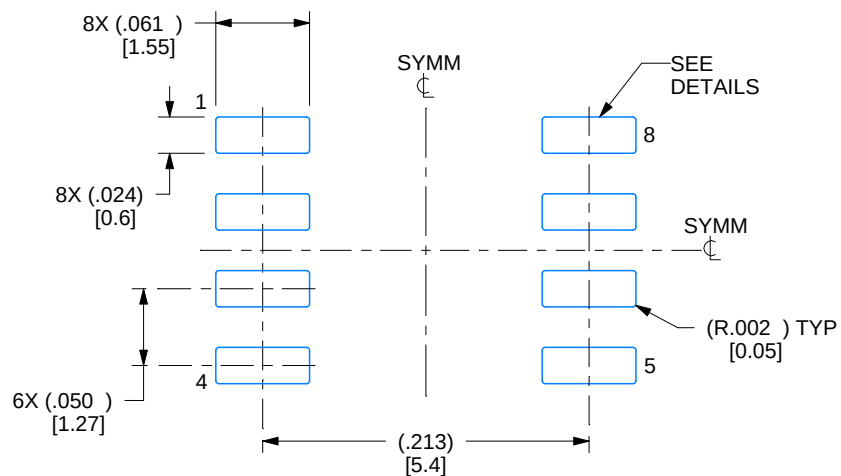


1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

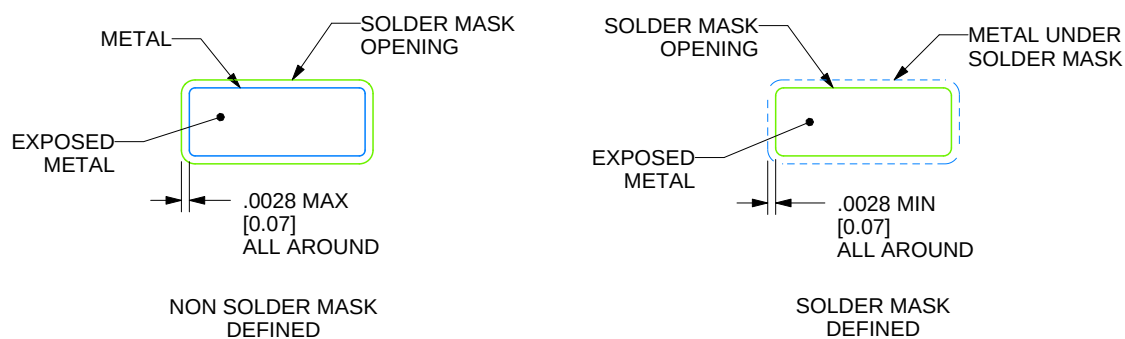
D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

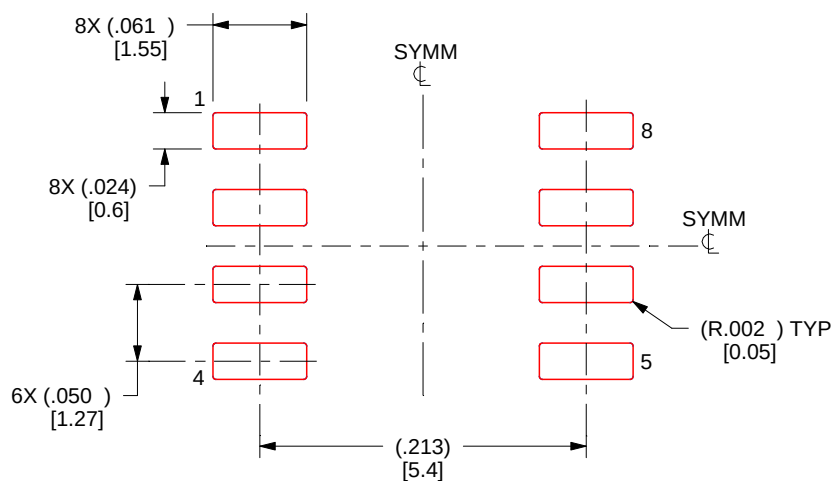
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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